![Image of a patent document with details filled out, including a name, address, and a date on May 24, 2006. The document involves an assignment and is related to a patent application with the number 11/193,758.](image-url)
ASSIGNMENT

For value received, I, Walter PROTSCH, an individual, residing at Neükkenstr. 7B, D-14513 Teltow, Germany; I, Juergen SCHULZE, an individual, residing at Patrizierweg 9A, D-14480 Potsdam, Germany, hereinafter assignors, hereby sell, assign and transfer to W.C. Heraeus GmbH, a corporation existing under the laws of Germany, located at Heraeusstr. 12-14, D-63450 Hanau, Germany, hereinafter assignee, and said assignee's successors, assigns, and legal representatives the entire right, title, and interest, for all countries including the United States of America, in and to certain inventions relating to METHOD FOR REFINING AND HOMOGENEously DISTRIBUTING ALLOYING PARTNERS AND FOR REMOVING UNDESIRABLE REACTION PRODUCTS AND SLAGS IN OR FROM SOFT SOLDER DURING THE PRODUCTION OF FINE SOLDER POWDER described in an application for Letters Patent of the United States, filed on July 28, 2005, and all patents which may be granted therefor, and all divisions, reissues, continuations and extensions thereof, and authorize and request the Commissioner of Patents and Trademarks to issue all patents on said improvements or resulting therefrom to said assignee as assignee of the entire interest, and covenant that said assignors have full right so to do, and agree that said assignors will communicate to said assignee or said assignee's representatives any facts known to said assignors respecting said improvements and testify in any legal proceedings, sign all lawful papers, execute all divisional, continuing and reissue applications, make all rightful oaths and generally do everything possible to aid said assignee,
and said assignee's successors, assigns, and nominees, to obtain and enforce proper protection for said invention in the United States.

Signature: Walter PROTSCHE
Date: 09/02/2005

Signature: Jürgen SCHULZE
Date: 09/02/2005